SolderStar PRO - VP

solderstar*
www.solderstar.com

Featuring SolderStar

smartlink*
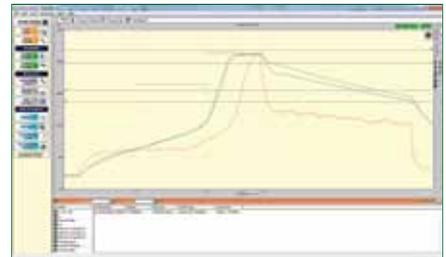connection System

Miniature Profling Datalogger
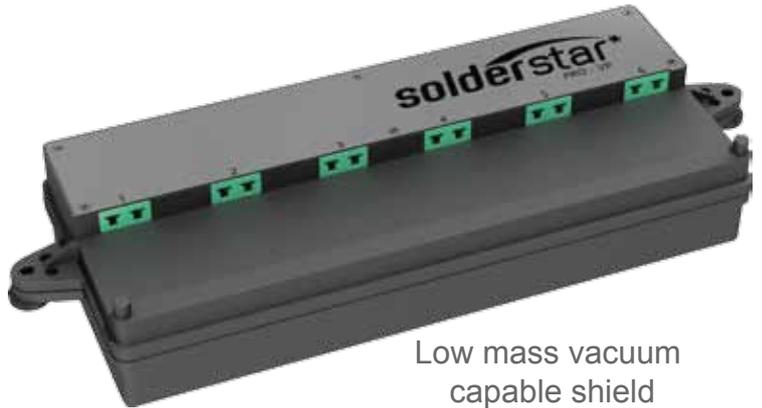
Low mass vacuum capable shield

PC Analysis Software with Vapour Phase process support

2.4Ghz Telemetry available providing datalink within vacuum stage machine

Vapour Phase Profiling for batch and inline machines

The SolderStar PRO - VP system allows users of batch and in-line vapour phase soldering machines to fully profile their products in the same way as a conventional reflow oven.

The system includes the SolderStar PRO data-logger combined with a sealed light-weight heat shield capable of operating in the pre-heat, vapour reflow and vacuum stages of the machine.

Data can be passed to a nearby PC via wireless telemetry allowing the profile to be viewed in real-time by the user.

Once data capture is complete the heat shield can be opened and the datalogger removed,allowing rapid cool down cycles and minimising the risk of overheating the profiling unit.

System Advantages

- Standard data logger and heat shield solution maximised datalogger protection

- Extendable for control of wave / selective or reflow soldering

- Unique SmartLink connection system provides quick datalogger connection to a range of products and accessories

- Low mass thermal shield provides minimal impact to process

- Error free Wireless Telemetry with automatic offload and catchup ensure no gaps in data transmission

- Extendable Wireless range > 100 Metres from machine

Datalogger   Technical Data

Size/Weight	125mm x 52mm x 9mm, 110g
Channels	upto 16 Channel Versions Available
Memory	120,000 Memory Points
Sampling	0.1s - 10 Minutes
Measurement Range	-150 - 600 °C
Accuracy	±0.5 °C
Resolution	±0.02 °C
Max. Internal Temperature	+85 °C (Auto Shutdown on over temp.)
Power	Rechargeable High Temperature Nimh
Communications	USB (Type A - Mini B) or 2.4Ghz Wireless
Thermocouples	Type K, EN 05842:1993 Class 1 / ANSI MC 96.1

Heatshield

Supplied Model	HS-VP006-01
Material	Aluminium - PTFE Coated
Weight	6 Channel Version: 620g

Thermal Protection Duration
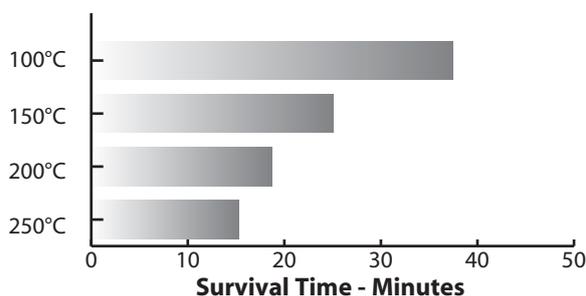
Other heatshield sizes are available for special process requirements.

Wireless Telemetry Option

Frequency	2.4GHZ Transceiver
Channels	128 Individual Channels
Protocol	Zigbee PRO - Duplex Transmission

Software

Compatibility	Windows™ XP Vista/Windows 7/8/10 32 & 64 Bit
Language Support	English, French, German, Italian, Portuguese, Spanish & Chinese

Standard Equipment

- 6 Channel Vapour Phase Barrier
- 6 Type K thermocouples
- Equipment case

This product can be supplied as a stand-alone system complete with datalogger, or as an accessory to an existing SolderStar system. Please contact SolderStar or your local supplier for the optimum configuration for your soldering processes.

Optional Equipment

- 8 Channel Barrier
- 2.4Ghz Wireless Telemetry
- USB powered Wireless range extender

Additional Process Support

REFLOW • WAVE • VAPOUR

A range of process specific accessories are available to extend the system for use with Reflow Wave/Selective Soldering and Vapour Phase processes.

Specification subject to change without notification

For more information contact your regional Solderstar office